

PEREGRINE MATERIAL DECLARATION FORM

Product:	PE64102
Ordering Codes:	PE64102B-Z
Description:	UltraCMOS® Digitally Tunable Capacitor (DTC) 100 - 3000 MHz
Package:	12L 2x2 QFN
Environmental Compliance	EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free
Lead Finish	NiPdAu
Availability	Now

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Aluminum oxide	1344-28-1	0.388719	5.645373%	56,453.73
Die	Aluminum	7429-90-5	0.001182	0.017172%	171.72
Die	Silicon	7440-21-3	0.000079	0.001145%	11.45
Die	Arsenic	7440-38-2	0.000001	0.000006%	0.06
Die	Boron	7440-42-8	0.000001	0.000006%	0.06
Die	Phosphorus	7723-14-0	0.000002	0.000023%	0.23
Die	Titanium	7440-32-6	0.000197	0.002862%	28.62
Die	Tungsten	7440-33-7	0.003941	0.057240%	572.40
Die	Cobalt	7440-48-4	0.000008	0.000114%	1.14
Die	Copper	7440-50-8	0.000003	0.000046%	0.46
Leadframe	Copper	7440-50-8	2.764500	40.148816%	401,488.16
Leadframe	Iron	7439-89-6	0.066600	0.967231%	9,672.31
Leadframe	Zinc	7440-66-6	0.003400	0.049378%	493.78
Leadframe	Phosphorus	7723-14-0	0.000900	0.013071%	130.71
Plating	Nickel	7440-02-0	0.026800	0.389216%	3,892.16
Plating	Palladium	7440-05-3	0.002100	0.030498%	304.98
Plating	Gold	7440-57-5	0.002100	0.030498%	304.98
Wire	Gold	7440-57-5	0.080500	1.169101%	11,691.01
Die Attach	Silver	7440-22-4	0.050900	0.739220%	7,392.20
Die Attach	Epoxy Resin	9003-36-5	0.012700	0.184442%	1,844.42
Die Attach	t-Butyl phenyl glycidyl ether	3101-60-8	0.005300	0.076972%	769.72
Die Attach	Phenolic hardener	92-88-6	0.001100	0.015975%	159.75
Die Attach	Butyl cellosolve acetate	112-07-2	0.000700	0.010166%	101.66
Mold Compound	Silica Fused	60676-86-0	3.185500	46.262997%	462,629.97
Mold Compound	Epoxy Resin	Trade secret	0.139000	2.018696%	20,186.96
Mold Compound	Phenol Resin	Trade secret	0.139000	2.018696%	20,186.96
Mold Compound	Carbon Black	1333-86-4	0.010400	0.151039%	1,510.39
Total Weight (mg)			6.885633	100.000000%	1,000,000